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6 AMP SILICON BRIDGE RECTIFIERS

FEATURES

- VOID FREE VACUUM DIE SOLDERING FOR MAXIMUM MECHANICAL STRENGTH AND HEAT DISSIPATION (Solder Voids: Typical < 2%, Max. < 10% of Die Area)
- **BUILT-IN STRESS RELIEF MECHANISM FOR** SUPERIOR RELIABILITY AND PERFORMANCE
- SURGE OVERLOAD RATING TO 250 AMPS PEAK
- IDEAL FOR PRINTED CIRCUIT BOARD APPLICATIONS
- THRU-HOLE FOR EASY HEAT SINK MOUNTING

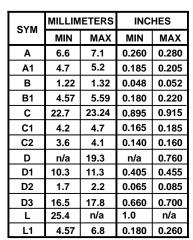
RECOGNIZED - FILE #E124962

MECHANICAL DATA

- Case: Molded plastic, U/L Flammability Rating 94V-0
- Terminals: Round silver plated pins •
- Soldering: Per MIL-STD 202 Method 208 guaranteed •
- Polarity: Marked on case
- Mounting Position: Any. Max. mounting torque = 5 in lb
- Weight: 0.3 Ounces (8 Grams)

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MECHANICAL SPECIFICATION SBU PACKAGE SHOWN ACTUAL SIZE



- B

SERIES SBU6A - SBU6M

MAXIMUM RATINGS & ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified. Single phase, 60Hz, resistive or inductive load. For capacitive loads, derate current by 20%

PARAMETER (TEST CONDITIONS)	SYMBOL	RATINGS							UNITS
Series Number		SBU 6A	SBU 6B	SBU 6D	SBU 6G	SBU 6J	SBU 6K	SBU 6M	
Maximum DC Blocking Voltage	Vrm	50	100	200	400	600	800	1000	
Maximum RMS Voltage	Vrms	35	70	140	280	420	560	700	VOLTS
Maximum Peak Recurrent Reverse Voltage	Vrrm	50	100	200	400	600	800	1000	
Average Forward Rectified Current $Tc = 100^{\circ}C$ (Notes 1, 3) $T_A = 40^{\circ}C$ (Note 2)	lo	6							AMPS
Peak Forward Surge Current. Single 60Hz Half-Sine Wave Superimposed on Rated Load (JEDEC Method). TJ = 150° C	Ігѕм	250							
Maximum Forward Voltage (Per Diode) at 6 Amps DC	Vfm	0.95 (Typical < 0.90)							VOLTS
Maximum Average DC Reverse Current@ TA = 25° CAt Rated DC Blocking Voltage@ TA = 100° C	Iгм	1 50							μΑ
Typical Thermal Resistance Junction to Ambient (Note 2) Junction to Case (Note 3)	RθJA RθJC	16.0 3.1							°C/W
Operating and Storage Temperature Range	Тј,Тѕтс	-55 to +150							°C

NOTES: (1) Bridge mounted on 2.6" x 1.4" x 0.06" thick (6.5cm x 3.5cm x 0.15cm) aluminum plate (2) Bridge mounted on PC Board with 0.5" sq. (12mm sq.) copper pads and bridge lead length of 0.375" (9.5mm) (3) Bolt bridge on heat sink with #6 screw, using silicon thermal compound between bridge and mounting surface for maximum heat transfer.

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RATING & CHARACTERISTIC CURVES FOR SERIES SBU6A - SBU6M

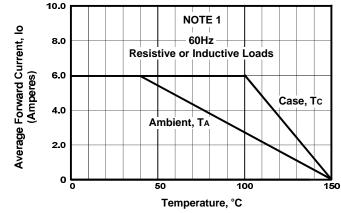


FIGURE 1. FORWARD CURRENT DERATING CURVE

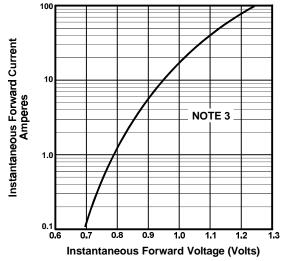


FIGURE 3. TYPICAL FORWARD CHARACTERISTIC PER DIODE

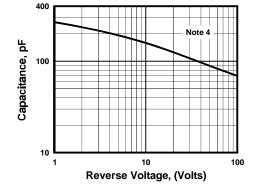


FIGURE 5. TYPICAL JUNCTION CAPACITANCE PER DIODE

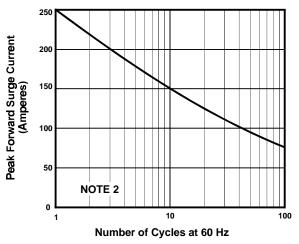


FIGURE 2. MAXIMUM NON-REPETITIVE SURGE CURRENT

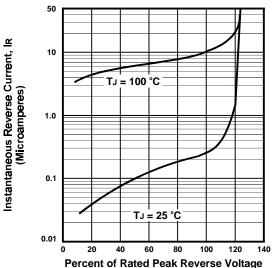


FIGURE 4. TYPICAL REVERSE CHARACTERISTICS

NOTES

(1) Case Temperature, Tc, With Bridge Mounted on 2.6" x 1.4" x 0.06" Thick (6.5cm x 3.5cm x 0.15cm) **Aluminum Plate**

Ambient Temperature, TA, With Bridge Mounted on PC Board With 0.5" Sq. (12mm Sq.) Pads and Bridge Lead Length of 0.375" (9.5mm)

(2) TJ = 150° C

(3) TJ = 25°C; Pulse Width = 300µSec; 1% Duty Cycle

(4) T_J = 25°C; f = 1 MHz; Vsig = 50mVp-p

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